

FIG. 1

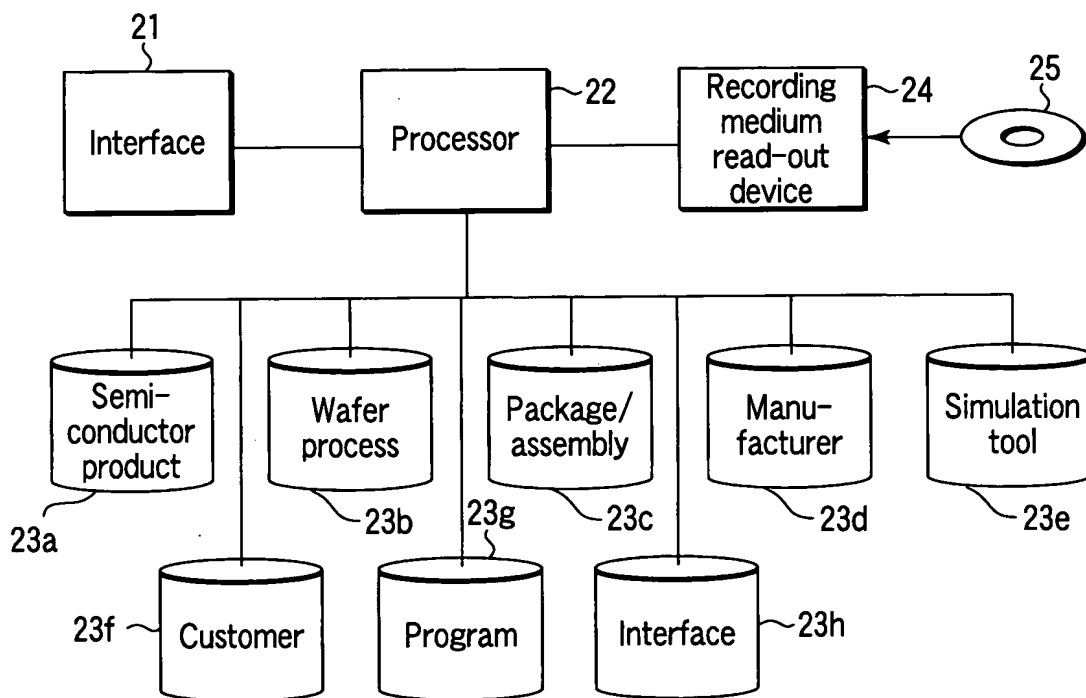


FIG. 2

20050506 6252600T

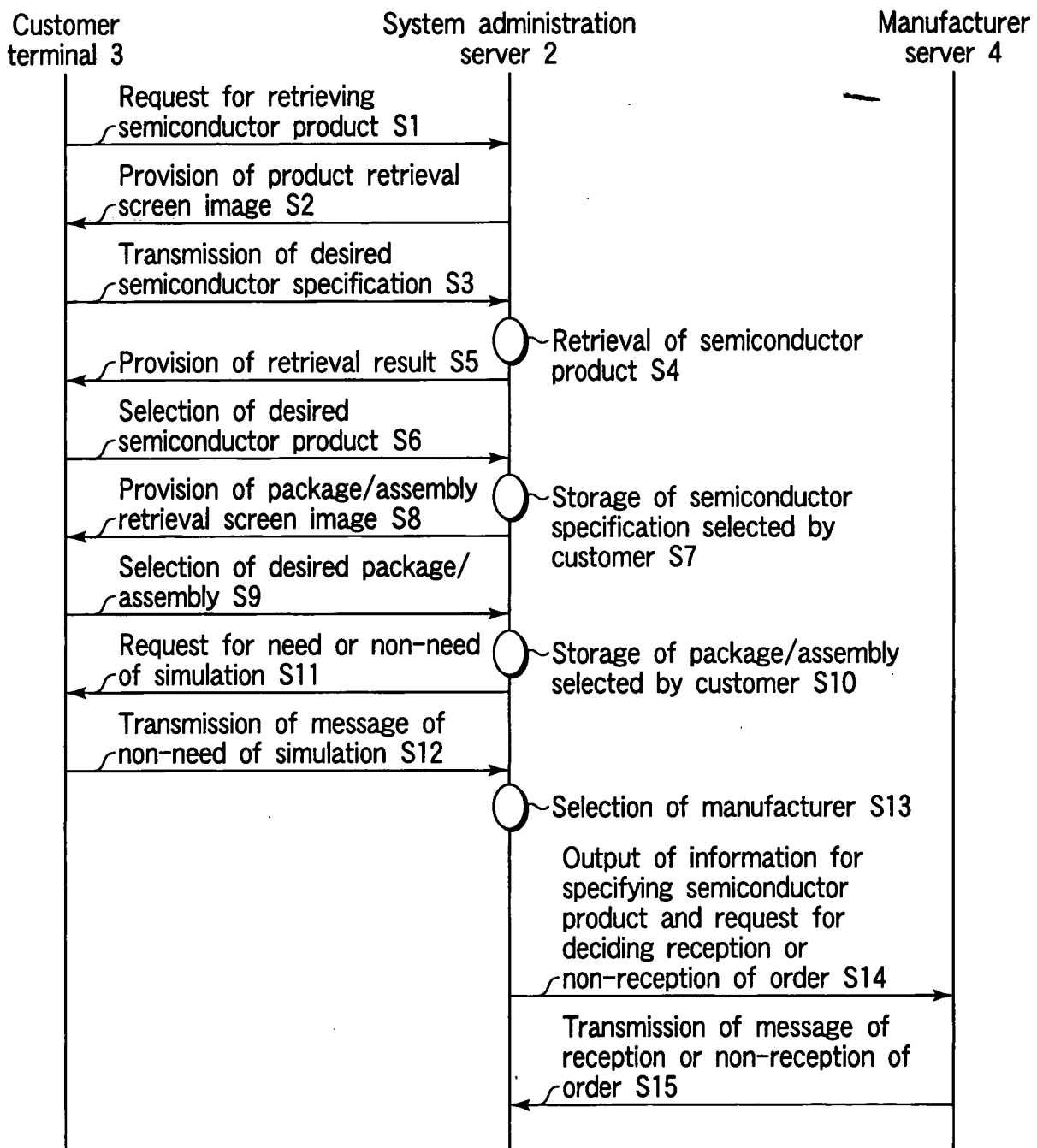


FIG. 3

20250206 62526007

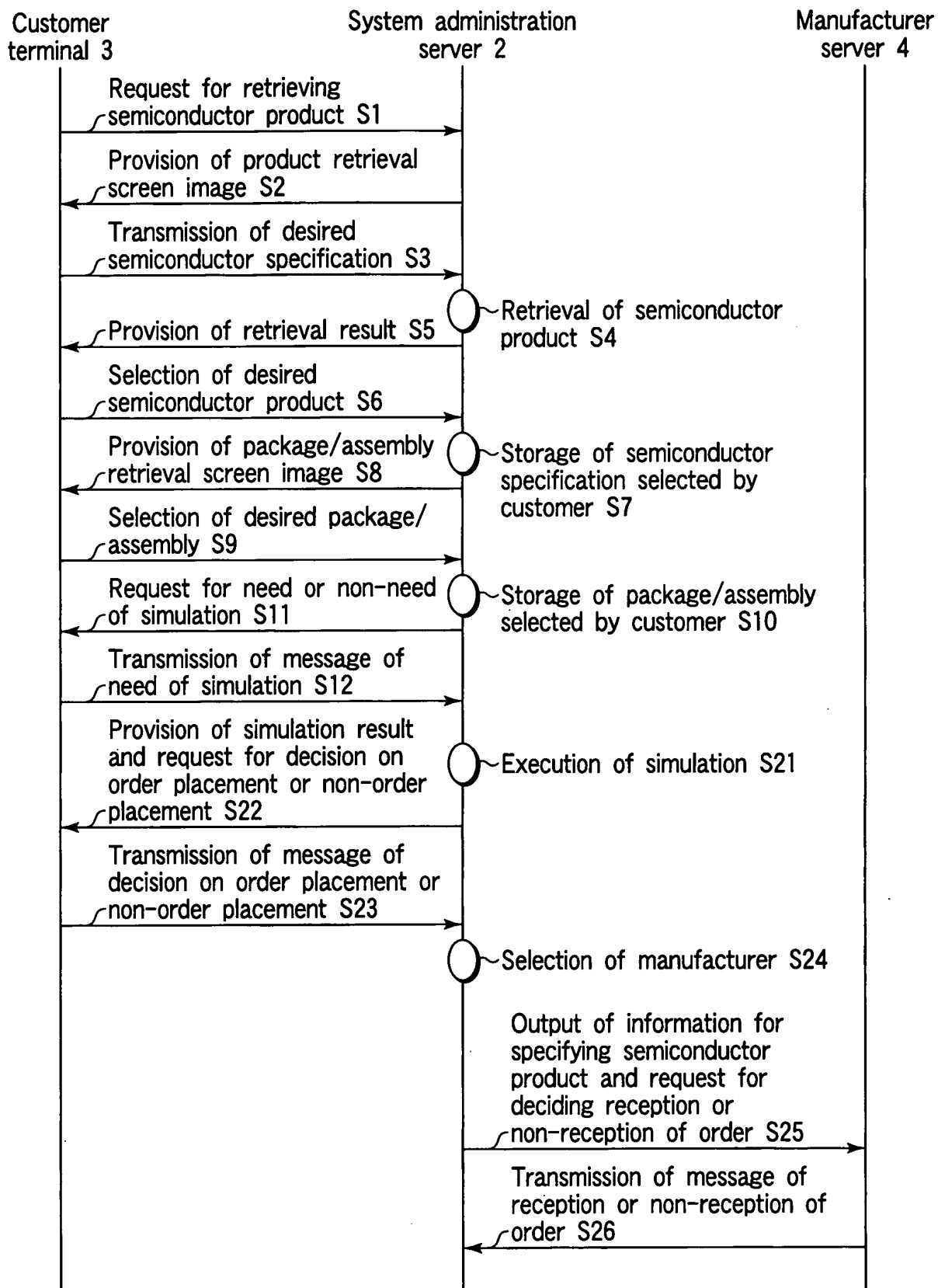


FIG. 4

THE UNIVERSITY OF CHICAGO

Select type of semiconductor product.
Also select specification of device you want to by selected
from list of typical devices below.

Memory	
Logic	
System LSI	
Others	

Input necessary specification.

Operation frequency MHz ~ MHz

Cost ¥ ~ ¥

Delivery date Not later than (month), (day)

OK Cancel

FIG. 5

Select product conforming to your specification form semiconductor products listed below.

System LSI, 800MHz

System LSI, 833MHz

System LSI, 850MHz

OK

Cancel

FIG. 6

Size

External form

Package type

Package structure

Inner lead bonding modes

Packing type for shipment

mm2 ~ mm2

☐BGA ☐DIP ☐QFP

☐Single chip ☐Multi-chip

☐Single layer ☐Multilayer

☐C4 ☐TAB ☐Wire

OK

Cancel

FIG.7

SECRET

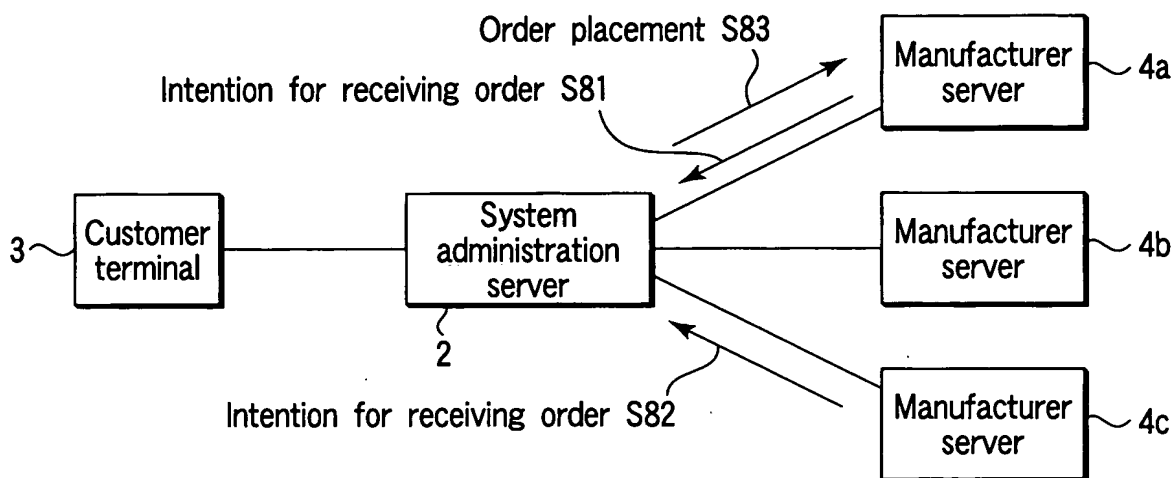


FIG. 8

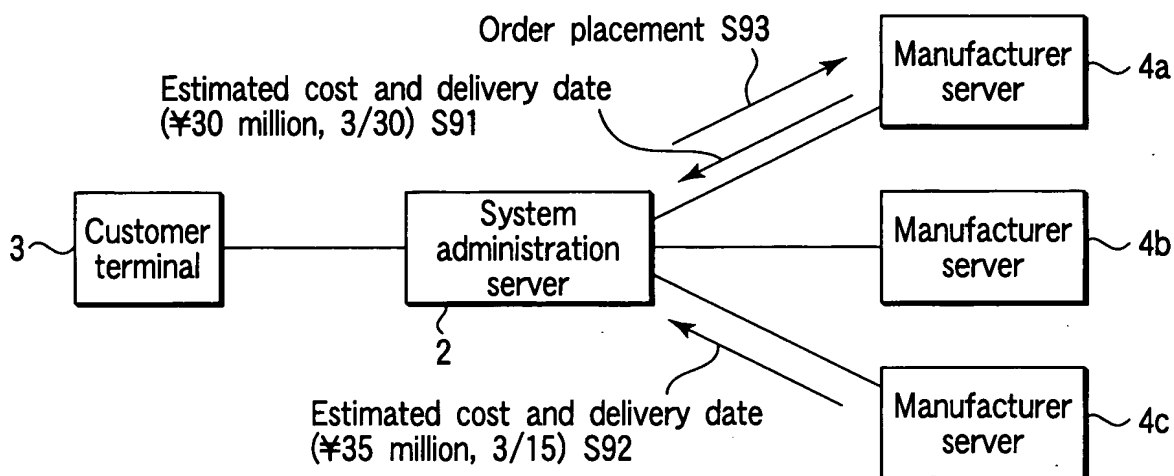


FIG. 9

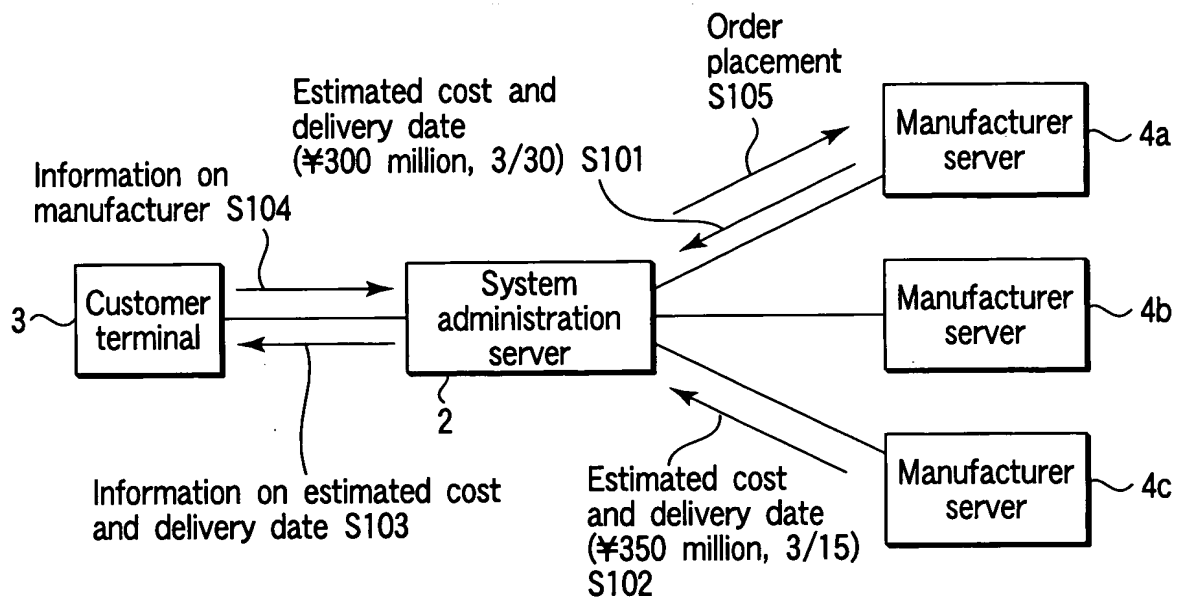


FIG. 10


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sequenceDiagram
    participant C3 as Customer terminal 3
    participant S2 as System administration server 2
    participant M4 as Manufacturer server 4

    C3->>S2: Request for retrieving semiconductor product S1
    S2->>C3: Provision of product retrieval program (provision of product retrieval screen image) S201
    C3->>C3: Input of desired semiconductor specification S301
    C3->>C3: Retrieval of semiconductor product S401
    C3->>C3: Display of retrieval result S501
    C3->>C3: Selection of desired semiconductor product S601
    C3->>C3: Storage of semiconductor specification selected by customer S701
    C3->>C3: Display of package/assembly retrieval screen image S801
    C3->>S2: Selection of desired package/assembly (transmission of package/assembly information and semiconductor specification) S901
    S2->>C3: Request for need or non-need of simulation S11
    C3->>S2: Transmission of message of need of simulation S12
    S2->>C3: Provision of simulation result and request for decision on order placement or non-order placement S22
    C3->>S2: Transmission of message of decision on order placement or non-order placement S23
    S2->>S2: Selection of manufacturer S24
    S2->>M4: Output of information for specifying semiconductor product and request for deciding reception or non-reception of order S25
    M4->>S2: Transmission of message of reception or non-reception of order S26
    
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FIG. 13